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## JP63194983 THERMALLY FUSIBLE HEAT-SENSITIVE TRANSFER SHEET **IWASAKI TSUNEO**

Inventor(s): ;OKABE TAKAYUKI Application No. 62028588, Filed 19870210, Published 19880812

## Abstract:

PURPOSE: To lower a surface tension of ink, to suppress noise during transfer operation and to improve resolution of printing by providing a transfer layer wherein thermally fusible ink is applied onto one face of supporting material, and incorporating thermoplastic resin having a specific softening temperature and silicone surfactant which is in liquid state at a specific temperature in the thermally fusible ink.

CONSTITUTION: In a thermally fusible transfer sheet having supporting material and a transfer layer formed by applying thermally fusible ink onto one face of the supporting material, the ink contains viscous thermoplastic resin having softening temperature of 50W120°C and silicone surfactant which is in liquid state at the temperature of at least 15W50°C. Supporting material includes film or paper. Thermoplastic resin includes ethylcellulose, polyester resin, petroleum resin, ethylene-vinyl acetate copolymer, etc. having high compatibility with binder and coloring agent and proper viscosity. Nonionic silicone surfactant having hydrophobic group composed of dimethyl silicone oil and hydrophilic group composed of polyether is employed.

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